ABSTRACT OF THE DISCLOSURE

A modular enclosure system for electronic equipment is disclosed as is a process for assembling such a system. The basic element of the system is a frame unit which forms a chamber for the electronic equipment. Each frame unit has front, rear and side openings. Around each opening is a flange and a push-on bulb seal. A generally rectangular cross-sectioned seal is adhered to corner posts of the frame unit. Doors are mounted to the frame unit to seal the front and rear openings by compressing respective bulb seals. Side panels are mounted to the frame unit to cover side openings of a single or multi-frame unit system and the side panels compress both types of seals mentioned above. Bridge panels connect adjoining, aligned frame units and compress the rectangular seals and also result in bulb seals mounted around adjoining side openings of adjoining frame units to compress each other. Battery housings, covers and skids are also connected to aligned frame units as is a single cap panel. The system is simple, economical, easy to handle, east to install and easy to expand.